

**WHAT IS CLAIMED IS:**

**1. A manufacturing apparatus comprising:**

a film formation chamber comprising an evaporation source opposing a substrate,  
5 means for moving the evaporation source in an X direction, and means for moving the substrate  
in a Y direction,

wherein a film is deposited on the substrate by repeating moving the evaporation source  
in the X direction and then moving the substrate in the Y direction at regular intervals.

10 **2. The manufacturing apparatus according to claim 1, wherein a plurality of the  
evaporation source are provided and move in parallel to each other.**

**3. The manufacturing apparatus according to claim 1, wherein the evaporation source is  
reciprocated in the X direction.**

15 **4. The manufacturing apparatus according to any one of claim 1, wherein the substrate  
is reciprocated in the Y direction in a film formation chamber.**

**5. A manufacturing apparatus comprising:**

20 a film formation chamber comprising means for moving a substrate in a Y direction;  
a setting chamber connected to the film formation chamber, the setting chamber  
comprising an evaporation source and means for moving the evaporation source in an X  
direction from the setting chamber into the film formation chamber,

25 wherein a film is deposited on the substrate by repeating moving the evaporation source  
in the X direction and then moving the substrate in the Y direction at regular intervals.

**6. The manufacturing apparatus according to claim 5, wherein a container storing an  
evaporation material is set in the evaporation source without being exposed to an atmosphere  
outside of the setting chamber.**

7. The manufacturing apparatus according to claim 5, wherein the setting chamber has a film thickness meter.

8. The manufacturing apparatus according to claim 5, wherein the film formation chamber and the setting chamber are connected to a vacuum discharge treatment chamber for vacuuming the chambers and have means for bringing in a material gas or a cleaning gas.

9. The manufacturing apparatus according to claim 5, wherein a plurality of the evaporation source are provided and move in parallel to each other.

10. The manufacturing apparatus according to claim 5, wherein the evaporation source is reciprocated in the X direction.

11. The manufacturing apparatus according to any one of claim 5, wherein the substrate is reciprocated in the Y direction in a film formation chamber.

12. A manufacturing apparatus comprising:  
a film formation chamber comprising a first evaporation source provided to be opposite to a substrate, first means for moving the first evaporation source in an X direction, a second evaporation source provided to be opposite to the substrate, second means for moving the second evaporation source in the X direction, and means for moving the substrate in a Y direction,  
wherein a film is deposited by repeatedly moving the substrate in the Y direction at regular intervals while making a movement speed of the first evaporation source in the X direction and a movement speed of the second evaporation source in the X direction different.

13. The manufacturing apparatus according to claim 12, wherein film thickness meters of adjacent first and second evaporation sources are disposed alternately so as to sandwich a movement pathway of the substrate.

14. The manufacturing apparatus according to claim 12, wherein the first and second

evaporation sources are reciprocated in the X direction.

15. The manufacturing apparatus according to any one of claim 12, wherein the substrate is reciprocated in the Y direction in a film formation chamber.

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16. A manufacturing apparatus comprising:

a loading chamber;

a delivery chamber connected to the loading chamber; and

a plurality of film formation chambers connected to the delivery chambers,

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wherein each of the plurality of the film formation chambers comprises a plurality of evaporation sources, means for moving the evaporation source in an X direction, and means for moving a substrate in a Y direction, and

wherein a film is deposited on the substrate by moving or reciprocating the evaporation sources in the X direction while moving the substrate in the Y direction at a constant speed.

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17. A method for manufacturing a semiconductor device comprising:

depositing a film over a substrate by repeating moving an evaporation source in an X direction and then moving the substrate in a Y direction at regular intervals.

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